

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2005-015915

(43)Date of publication of application : 20.01.2005

(51)Int.Cl. C23C 14/34

(21)Application number : 2004-165444

(71)Applicant : SHOWA DENKO KK

(22)Date of filing : 03.06.2004

(72)Inventor : SUGANO YOSHIHARU

(30)Priority

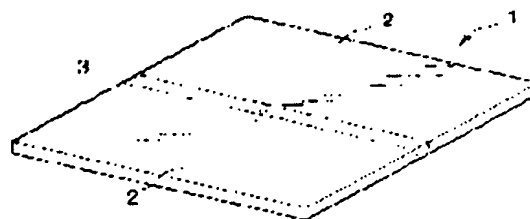
Priority number : 2003160250 Priority date : 05.06.2003 Priority country : JP

(54) SPUTTERING TARGET, AND ITS PRODUCTION METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a large-sized sputtering target which can be produced at a relatively low cost, and in which the intrusion of impurities can be suppressed.

SOLUTION: The sputtering target 1 is formed by arranging a plurality of planar target constituting members 2 in the same plane and subjecting the members to friction stir joining each other. In the method of producing the sputtering target 1, a plurality of planar target constituting members 2 are arranged in the same plane so that the adjoining ones are abutted on each other, a probe of a tool for friction stir joining is implanted in the abutted part of the adjoining target constituting members 2 so as to be laid across the both. Thereafter, the target constituting members 2 and the probe are relatively moved, so that the probe 2 is moved over the whole length of the abutted part, and the target constituting members 2 are mutually subjected to friction stir joining.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office